

IMPI 53 Registrants*last updated June 6, 2019*

Badge First Name	Badge Last Name	Badge Organization	Country
Benone	Achiriloaie	Macom Technology Solutions	USA
Kosiantyn	Achkasov	SAIREM	France
Art	Aguayo	Rogers Corporation	USA
Juan	Aguilar-Garib	Univesity of Nuevo Leon	Mexico
Andres	Angelo	Macom	Netherlands
Fatima	Arrutia Rodriguez	University of Nottingham	United Kingdom
Klaus	Baumgaertner	Muegge GmbH	Germany
Luciano	Bellemo	Unox SpA	Italy
Henk	Berkel	Multek	China
Jean-Paul	Bernard	SAIREM	France
Eleanor	Binner	University of Nottingham	United Kingdom
Brian	Blackwell	Odyssey Technical Solutions	USA
Glenn	Blaker	PSC, Inc. / C.A. Litzler Corp.	USA
Scott	Blaker	RF Specialists Ltd	Canada
Ray	Boxman	Tel Aviv University	Israel
Fernando	Bressan	Cartigliano SpA	Italy
Graham	Brodie	The University of Melbourne	Australia
Larry	Broome	Odyssey Technical Solutions	USA
Tab	Burkman	Conagra Brands	USA
Mario	Cammarota	Unox SpA	Italy
David	Castillo	TurboChef	USA
Jose Manuel	Catala-Civera	Universitat Politecnica de Valencia	Spain
Jiajia	Chen	University of Tennessee	USA
Su-Der	Chen	National Ilan University	Taiwan
Ed	Cook	ACP Inc.	USA
Jerome	Czajkowski	Muegge-Gerling	USA
Steven	Drucker	Droaster Laboratories LLC	USA
Christian	Ducrot	DEMMOS	France
Greg	Durnan	Kent State University	USA
Candice	Ellison	Leidos, Nat'l Energy Technology Laboratory	USA
Ulrich	Erle	Nestle R&D	USA
Kenneth	Foster	University of Pennsylvania	USA
Wenjie	Fu	University of Electronic Science and Technology	China
Francesco	Garuti	MKS	Italy
Marco	Garuti	MKS	Italy
Paola	Garuti	MKS	Italy
Lucas	Gerads	Aixcon PowerSystems GmbH	Germany
Paul	Gerhardt	JBT Corporation	USA
John F.	Gerling	Gerling Consulting	USA
Philip	Gilchrist	TE CONNECTIVITY	USA
Chuting	Gong	Shanghai Jiao Tong University	China
Moritz	Gorath	Muegge GmbH	Germany

Mike	Greenlee	Multek	USA
Hannes	Grubinger	HUBER+SUHNER AG	Switzerland
Ben	Hamer	JBT Corporation	USA
Andrew	Hawryluk	LytEn	USA
Stephan	Holtrup	pinkRF	Netherlands
Christopher	Hopper	ITW	USA
Satoshi	Horikoshi	Sophia University	Japan
Rachel	Huang	Wattsine Electronics	China
Stephanie	Jarno	HUBER+SUHNER AG	Switzerland
Yang	Jiao	Shanghai Ocean University	China
Marie	Jirsa	Tyson Foods	USA
Humayan	Kabir	University of Melbourne	Australia
Mohammad	Kamarehi	MKS, ASTeX Product Group	USA
Kenneth	Kaplan	Cellencor, Inc.	USA
Jin	Kim	Maltani Corporation	South Korea
KJ	Kim	AllianceNP	South Korea
Christian	Koenen	RATIONAL	Germany
Philip	Knights	Macom	USA
Bernard	Krieger	Cober, Inc.	USA
Matthew	Krieger	Cober, Inc.	USA
Enver	Krvavac	Crescend Technologies	USA
Petra	Kumi	Worcester Polytechnic Institute	USA
Alain	Le Bail	ONIRIS	France
Patricia	Le Bail	INRA BIA	France
Boram	Lee	WAVEPIA Co., Ltd.	South Korea
Sanghun	Lee	WAVEPIA Co., Ltd.	South Korea
Matthew	Leeds	Transform Materials LLC	USA
David	Lester	NXP Semiconductors	USA
Jan	Lindholm	Dipolar AB	Sweden
Paul	Loughnane	TE CONNECTIVITY	USA
Donglei	Luan	Shanghai Ocean University	China
Jennifer	Marshall-Jenkinson	MTA-UK	United Kingdom
John	Mastela	Crescend Technologies	USA
Peter	Matthews	Mega Industries, LLC	USA
Sean	McKeown	Graphic Packaging International	USA
Tomohiko	Mitani	Kyoto University	Japan
Rasheed	Mohammed	Campbell Soup Company	USA
John	Morelli	IW Microwave Products	USA
Robert	Mueller	Gerling Applied Engineering, Inc. (a Muegge	Germany
Rick	Myer	Communication Power Corporation	USA
Franck	Nicholls	NXP Semiconductor	USA
Vijay	Patel	Teledyne e2v US	USA
Dana	Pearson	Graphic Packaging International	USA
Molly	Poisant	IMPI	USA
Birgitta	Raaholt	Research Institute of Sweden	Sweden
Marilena	Radoiu	Radiant Technologies	Canada

Vasielos	Ramopolous	Karlsruhe Institute of Technology	Germany
Rick	Rigby	3D RF Energy Corp	USA
Adam	Ritscher	Ampleon	USA
Walter	Rönblom	Dipolar AB	Sweden
Nicholas	Roy	ACP, Inc.	USA
Robert F.	Schiffmann	R.F. Schiffmann Associates	USA
Dale	Schumann	Marion Process Solutions	USA
Igor	Semenov	Leibniz Institute for Plasma Science and Tech	Germany
Steven	Simons	IBF Electronic GmbH	German
Alicia	Standridge	IMPI	USA
Don	Stull	Microzap	USA
Ali	Taqi	University of Nottingham	United Kingdom
Fraser	Tibbetts	Ferrite Microwave Technologies	USA
Peter	Tibbetts	Ferrite Microwave Technologies	USA
Patrick	Valk	Ampleon	The Netherlands
David	Vennin	SAIREM	France
Mark	Watts	Campbell Soup Company	USA
Klaus	Werner	pinkRF	Netherlands
Jerry	Wessel	Richardson Electronics	USA
Robin	Wesson	Macom	Netherlands
Roger	Williams	3D RF Energy Corp	USA
Wilson	Yen	TE CONNECTIVITY	USA
Carsten	Winnewisser	TRUMPF Hüttinger GmbH	Germany
Michael	Wolf	Smart Kitchen Summit/The Spoon	USA
Douglas	Woodruff	JBT Corporation	USA
Zhe	Wu	University of Electronic Science and Tech	China
Vadim	Yakovlev	Worcester Polytechnic Institute	USA
Yang	Yang	Sichuan University	China
Frank	Younce	Washington State University	USA
Hangjin	Zhang	Shanghai Jiao Tong University	China
Huacheng	Zhu	Sichuan University	China